

IN THE CLAIMS:

Please CANCEL claims 1-40 without prejudice to or disclaimer of the recited subject matter.

Please ADD new claims 41-52, as follows. For the Examiner's convenience, all claims currently pending in this application have been reproduced below:

1-40. (Cancelled)

41. (New) A scanning exposure apparatus for exposing a substrate to a pattern, said apparatus comprising:

an exposure system which exposes the substrate to the pattern with respect to a unit region, to which the pattern is transferred, of the substrate;

a determination system which determines whether a condition of an exposure performed by said exposure system is allowable during the exposure; and

a control system which causes said exposure system to continue exposing a remaining region in the unit region of the substrate to the pattern, even after said determination system makes a negative determination for the unit region.

42. (New) An apparatus according to claim 41, wherein the condition of the exposure includes a position of a region of the substrate.

43. (New) An apparatus according to claim 42, wherein the position is a position in a direction along which the pattern is projected.

44. (New) An apparatus according to claim 41, wherein the condition of the exposure includes a precision of an exposure control performed by said exposure system.

45. (New) An apparatus according to claim 44, wherein the precision of the exposure control includes at least one of an alignment sync control precision and an exposure amount control precision.

46. (New) A device manufacturing method comprising:
a step of exposing a substrate to a pattern using an exposure apparatus defined in claim 41.

47. (New) A scanning exposure apparatus for exposing a substrate to a pattern, said apparatus comprising:
an exposure system which exposes the substrate to the pattern with respect to a unit region, to which the pattern is transferred, of the substrate;
a determination system which determines whether a condition of an exposure performed by said exposure system is allowable during the exposure;

a control system which causes said exposure system to expose a complete region in the unit region of the substrate to the pattern, even if said determination system makes a negative determination for the unit region; and

a display system which discriminately displays the unit region, for which said determination system makes the negative determination, of the substrate.

48. (New) An apparatus according to claim 47, wherein the condition of the exposure includes a position of a region of the substrate.

49. (New) An apparatus according to claim 48, wherein the position is a position in a direction along which the pattern is projected.

50. (New) An apparatus according to claim 47, wherein the condition of the exposure includes a precision of an exposure control performed by said exposure system.

51. (New) An apparatus according to claim 50, wherein the precision of the exposure control includes at least one of an alignment sync control precision and an exposure amount control precision.

52. (New) A device manufacturing method comprising:
a step of exposing a substrate to a pattern using an exposure apparatus defined in claim 47.